

MOS FIELD EFFECT TRANSISTOR

2SJ355

P-CHANNEL MOS FET FOR HIGH SWITCHING

The 2SJ355 is a P-channel MOS FET of a vertical type and is a switching element that can be directly driven by the output of an IC operating at 5 V.

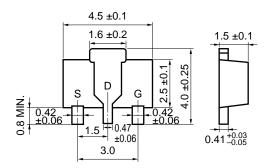
This product has a low ON resistance and superb switching characteristics and is ideal for driving the actuators and DC/DC converters.

FEATURES

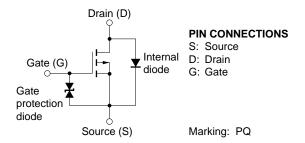
- · Can be directly driven by 5-V IC
- · Low ON resistance

R_{DS(on)} = 0.60 Ω MAX. @V_{GS} = -4 V, I_D = -1.0 A R_{DS(on)} = 0.35 Ω MAX. @V_{GS} = -10 V, I_D = -1.0 A

PACKAGE DIMENSIONS (in mm)



EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

PARAMETER	SYMBOL	TEST CONDITIONS	RATING	UNIT
Drain to Source Voltage	Voss	V _G S = 0	-30	V
Gate to Source Voltage	Vgss	V _{DS} = 0	-20/+10	V
Drain Current (DC)	I _{D(DC)}		±2.0	Α
Drain Current (Pulse)	I _{D(pulse)}	PW ≤ 10 ms	±4.0	Α
		Duty cycle ≤ 1 %		
Total Power Dissipation	Рт	16 cm $^2 \times 0.7$ mm, ceramic substrate used	2.0	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

The internal diode connected between the gate and source of this product is to protect the product from static electricity. If the product is used in a circuit where the rated voltage of the product may be exceeded, connect a protection circuit.

Take adequate preventive measures against static electricity when handling this product.

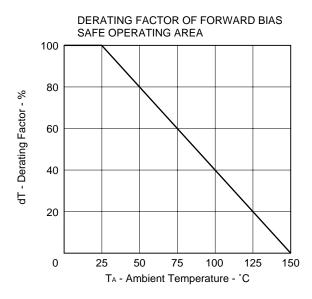
The information in this document is subject to change without notice.

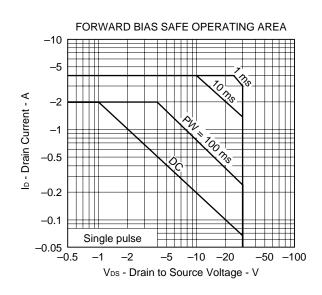


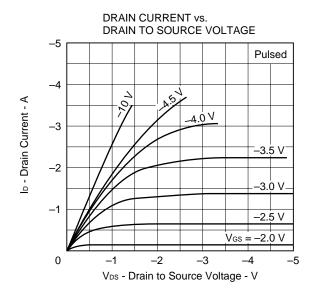
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

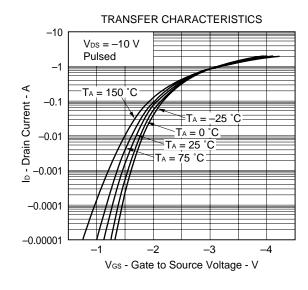
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain Cut-Off Current	IDSS	V _{DS} = -30 V, V _{GS} = 0			-10	μΑ
Gate Leakage Current	Igss	Vgs = -16/+10 V, Vps = 0			±10	μΑ
Gate Cut-Off Voltage	V _{GS(off)}	V _{DS} = −10 V, I _D = −1 mA	-1.0	-1.5	-2.0	V
Forward Transfer Admittance	y _{fs}	$V_{DS} = -10 \text{ V}, I_{D} = -1.0 \text{ A}$	1.0			S
Drain to Source On-State Resistance	R _{DS(on)1}	$V_{GS} = -4 \text{ V}, I_{D} = -1.0 \text{ A}$		0.50	0.60	Ω
Drain to Source On-State Resistance	R _{DS(on)2}	Vgs = -10 V, ID = -1.0 A		0.26	0.35	Ω
Input Capacitance	Ciss	V _{DS} = -10 V, V _{GS} = 0, f = 1.0 MHz		300		pF
Output Capacitance	Coss			245		pF
Reverse Transfer Capacitance	Crss			120		pF
Turn-On Delay Time	td(on)	$V_{DD} = -25$ V, $I_{D} = -1.0$ A $V_{GS(on)} = -10$ V $R_{G} = 10$ Ω, $R_{L} = 25$ Ω		5.5		ns
Rise Time	tr			32		ns
Turn-Off Delay Time	td(off)			110		ns
Fall Time	tf			130		ns
Gate Input Charge	Q _G	V _{DS} = -24 V, V _{GS} = -10 V, I _D = -1.8 A, I _G = -2 mA		12.2		nC
Gate to Source Charge	Qgs			1.2		nC
Gate to Drain Charge	Q _{GD}			4.6		nC
Internal Diode Reverse Recovery Time	trr	$I_F = 2.0 \text{ A},$ $di/dt = 50 \text{ A}/\mu\text{s}$		95		ns
Internal Diode Reverse Recovery Charge	Qrr			85		nC

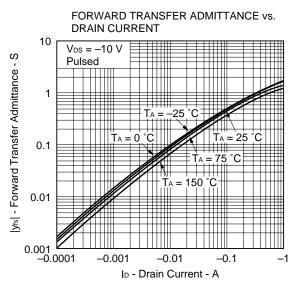
TYPICAL CHARACTERISTICS (TA = 25 °C)

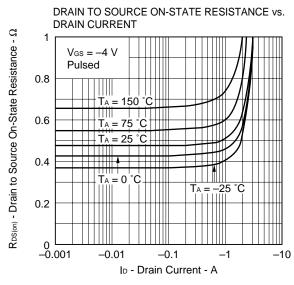


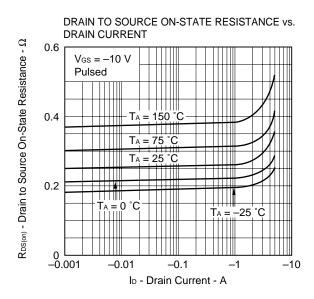


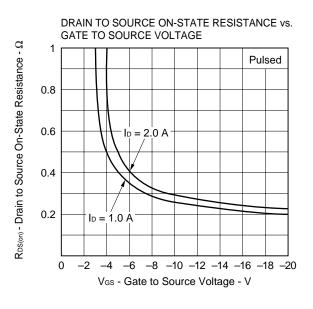




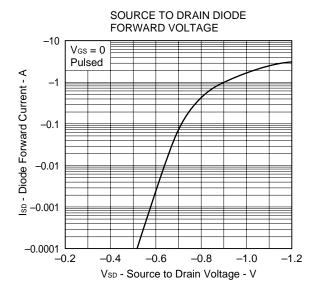


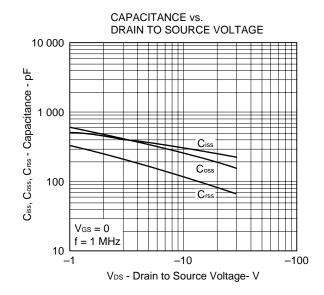


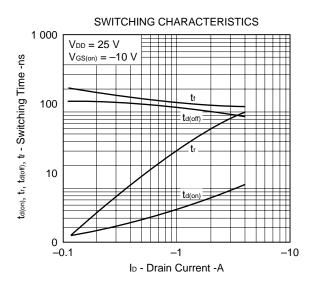


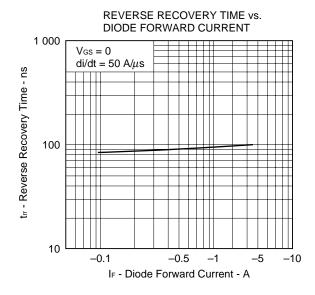


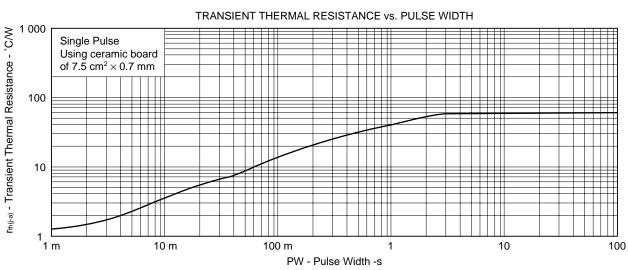














REFERENCE

Document Name	Document No.		
NEC semiconductor device reliability/quality control system	TEI-1202		
Quality grade on NEC semiconductor devices	IEI-1209		
Semiconductor device mounting technology manual	C10535E		
Guide to quality assurance for semiconductor devices	MEI-1202		
Semiconductor selection guide	X10679E		

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Anti-radioactive design is not implemented in this product.